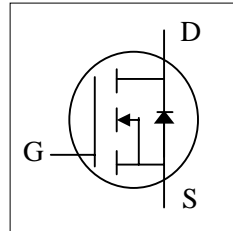
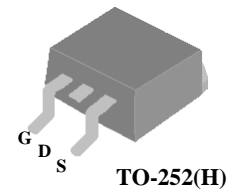




- ▼ Low On-resistance
- ▼ Simple Drive Requirement
- ▼ Fast Switching Characteristic



BV_{DSS}	40V
$R_{DS(ON)}$	3.7m Ω
I_D	75A



Description

Advanced Power MOSFETs from APEC provide the designer with the best combination of fast switching, ruggedized device design, low on-resistance and cost-effectiveness.

The TO-252 package is widely preferred for commercial-industrial surface mount applications and suited for low voltage applications such as DC/DC converters.

Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V_{DS}	Drain-Source Voltage	40	V
V_{GS}	Gate-Source Voltage	+20	V
$I_D@T_C=25^\circ C$	Continuous Drain Current (Chip)	125	A
$I_D@T_C=25^\circ C$	Continuous Drain Current ⁴	75	A
$I_D@T_C=100^\circ C$	Continuous Drain Current ⁴	75	A
I_{DM}	Pulsed Drain Current ¹	300	A
$P_D@T_C=25^\circ C$	Total Power Dissipation	104	W
T_{STG}	Storage Temperature Range	-55 to 150	$^\circ C$
T_J	Operating Junction Temperature Range	-55 to 150	$^\circ C$

Thermal Data

Symbol	Parameter	Value	Units
R_{thj-c}	Maximum Thermal Resistance, Junction-case	1.2	$^\circ C/W$
R_{thj-a}	Maximum Thermal Resistance, Junction-ambient (PCB mount) ³	62.5	$^\circ C/W$



AP3R604GH-HF

Electrical Characteristics @T_j=25°C(unless otherwise specified)

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V, I _D =250uA	40	-	-	V
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =10V, I _D =40A	-	-	3.7	mΩ
		V _{GS} =4.5V, I _D =30A	-	-	5.6	mΩ
V _{GS(th)}	Gate Threshold Voltage	V _{DS} =V _{GS} , I _D =250uA	1	-	3	V
g _{fs}	Forward Transconductance	V _{DS} =10V, I _D =40A	-	100	-	S
I _{DSS}	Drain-Source Leakage Current	V _{DS} =40V, V _{GS} =0V	-	-	10	uA
I _{GSS}	Gate-Source Leakage	V _{GS} =±20V, V _{DS} =0V	-	-	±100	nA
Q _g	Total Gate Charge	I _D =40A	-	28	45	nC
Q _{gs}	Gate-Source Charge	V _{DS} =32V	-	5.3	-	nC
Q _{gd}	Gate-Drain ("Miller") Charge	V _{GS} =4.5V	-	16	-	nC
t _{d(on)}	Turn-on Delay Time	V _{DS} =20V	-	10	-	ns
t _r	Rise Time	I _D =40A	-	80	-	ns
t _{d(off)}	Turn-off Delay Time	R _G =3.3 Ω	-	36	-	ns
t _f	Fall Time	V _{GS} =10V	-	105	-	ns
C _{iss}	Input Capacitance	V _{GS} =0V	-	2750	4400	pF
C _{oss}	Output Capacitance	V _{DS} =25V	-	600	-	pF
C _{riss}	Reverse Transfer Capacitance	f=1.0MHz	-	175	-	pF
R _g	Gate Resistance	f=1.0MHz	-	1.5	2.3	Ω

Source-Drain Diode

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Units
V _{SD}	Forward On Voltage ²	I _S =40A, V _{GS} =0V	-	-	1.2	V
t _{rr}	Reverse Recovery Time	I _S =10A, V _{GS} =0V,	-	45	-	ns
Q _{rr}	Reverse Recovery Charge	dI/dt=100A/μs	-	58	-	nC

Notes:

- 1.Pulse width limited by max. junction temperature
- 2.Pulse test
- 3.Surface mounted on 1 in² copper pad of FR4 board
- 4.Package limitation current is 75A .

THIS PRODUCT IS SENSITIVE TO ELECTROSTATIC DISCHARGE, PLEASE HANDLE WITH CAUTION.

USE OF THIS PRODUCT AS A CRITICAL COMPONENT IN LIFE SUPPORT OR OTHER SIMILAR SYSTEMS IS NOT AUTHORIZED.

APEC DOES NOT ASSUME ANY LIABILITY ARISING OUT OF THE APPLICATION OR USE OF ANY PRODUCT OR CIRCUIT DESCRIBED HEREIN; NEITHER DOES IT CONVEY ANY LICENSE UNDER ITS PATENT RIGHTS, NOR THE RIGHTS OF OTHERS.

APEC RESERVES THE RIGHT TO MAKE CHANGES WITHOUT FURTHER NOTICE TO ANY PRODUCTS HEREIN TO IMPROVE RELIABILITY, FUNCTION OR DESIGN.

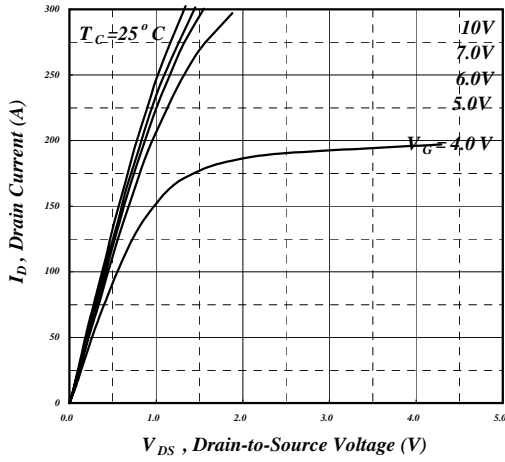


Fig 1. Typical Output Characteristics

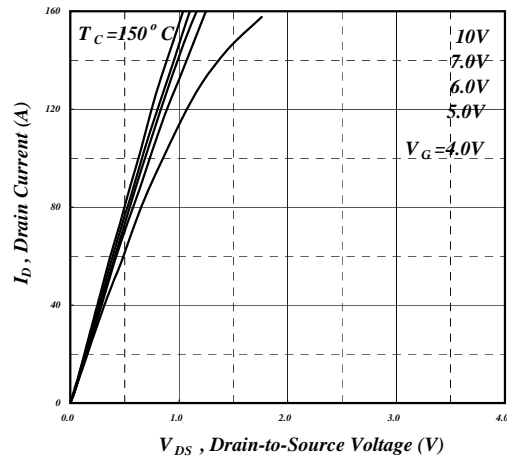


Fig 2. Typical Output Characteristics

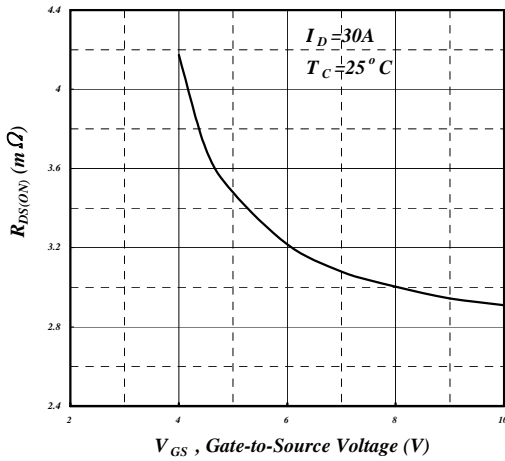


Fig 3. On-Resistance v.s. Gate Voltage

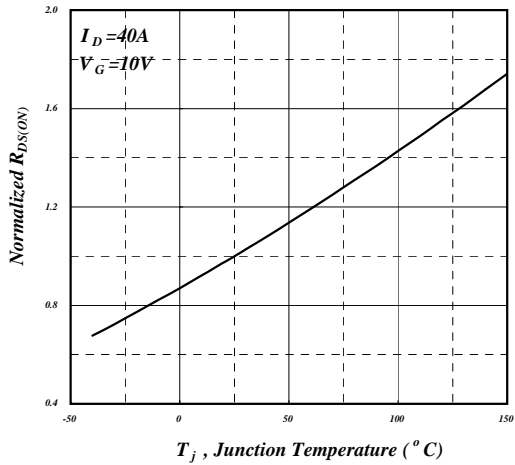


Fig 4. Normalized On-Resistance v.s. Junction Temperature

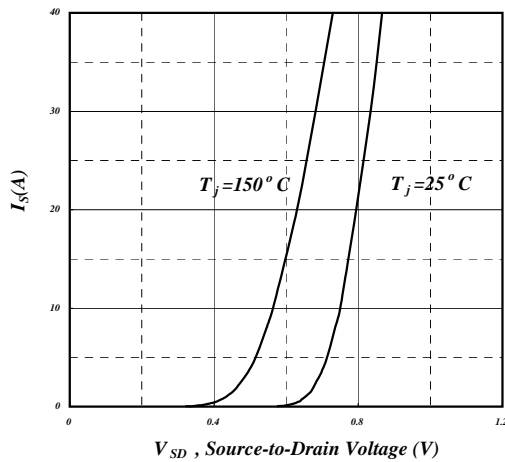


Fig 5. Forward Characteristic of Reverse Diode

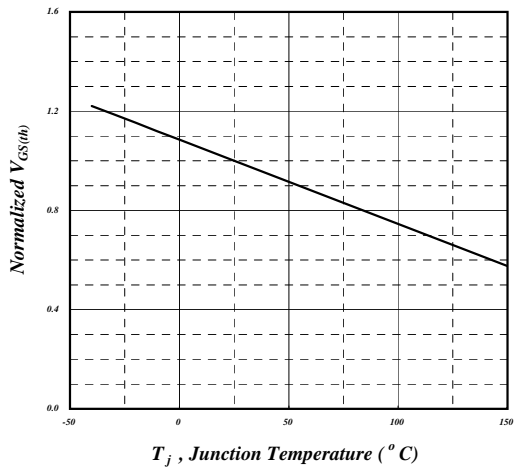


Fig 6. Gate Threshold Voltage v.s. Junction Temperature

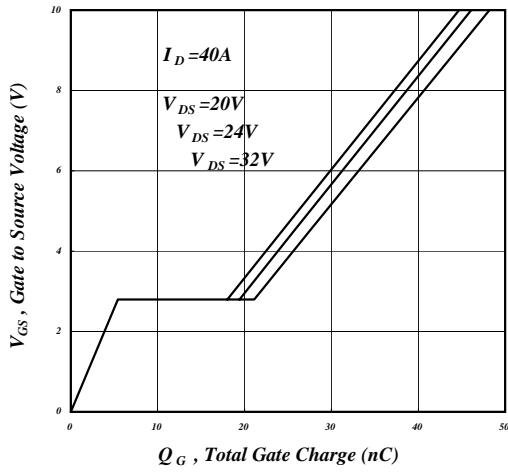


Fig 7. Gate Charge Characteristics

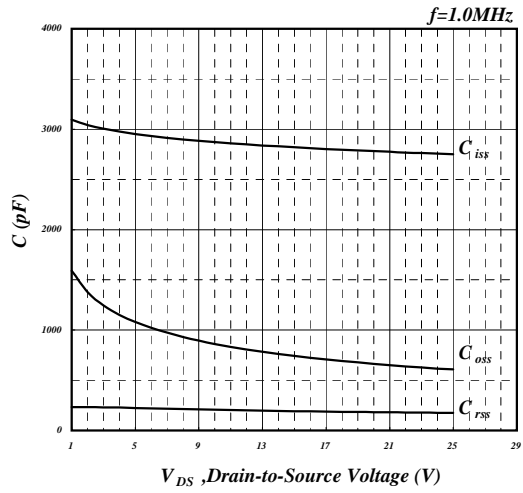


Fig 8. Typical Capacitance Characteristics

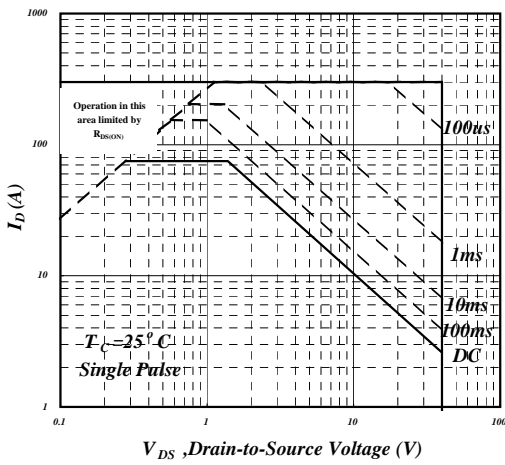


Fig 9. Maximum Safe Operating Area

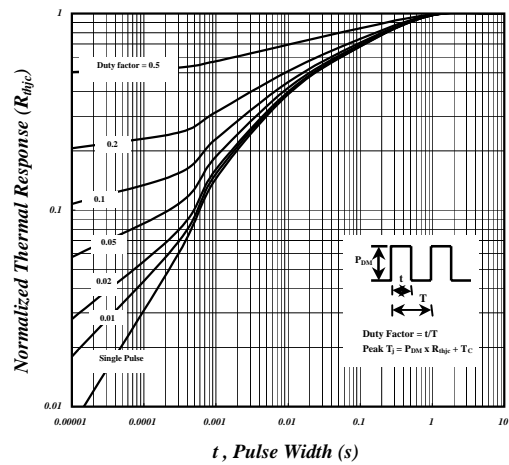


Fig 10. Effective Transient Thermal Impedance



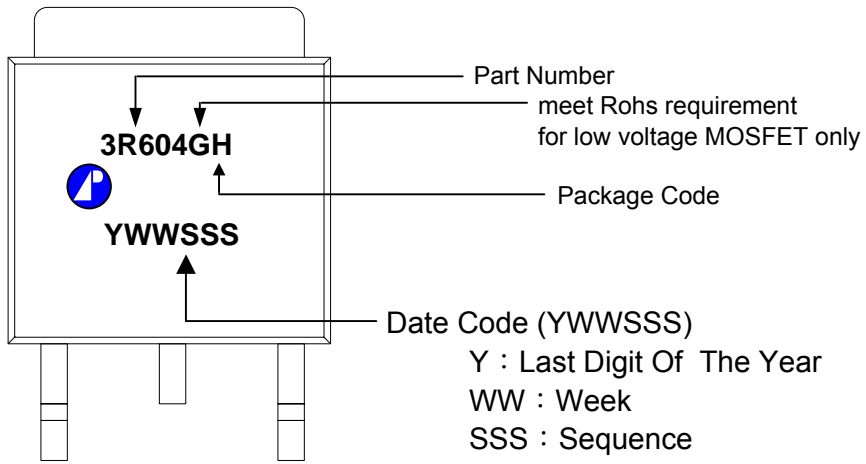
Fig 11. Switching Time Waveform



Fig 12. Gate Charge Waveform

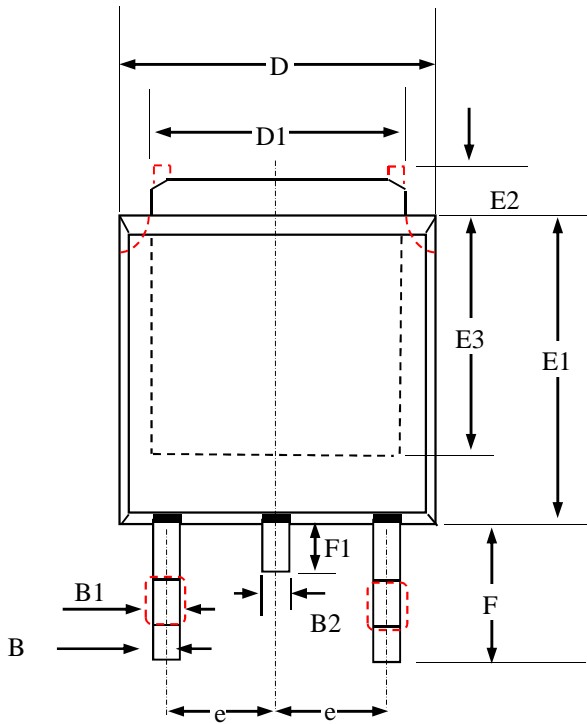


MARKING INFORMATION





Package Outline : TO-252



SYMBOLS	Millimeters		
	MIN	NOM	MAX
A2	2.18	2.30	2.40
A3	0.40	0.50	0.65
B	0.40	0.70	1.00
B1	0.50	0.85	1.20
D	6.00	6.50	6.80
D1	4.80	5.35	5.90
E3	4.00 (ref.)		
F	2.00	2.63	3.05
F1	0.50	0.85	1.20
E1	5.00	5.70	6.30
E2	0.50	1.10	1.80
e	2.3 (ref)		
C	0.35	0.525	0.70
A1	0.00	—	0.25
B2	—	—	1.25
L	0.90	1.34	1.78



1. All Dimensions Are in Millimeters.
2. Dimension Does Not Include Mold Protrusions.
3. Thermal PAD, Body and Pin contour is for reference, it may has little difference by option.



TO-252 FOOTPRINT :

